

Negative Fixed 5V Voltage Regulator in bare die form

Rev 1.0 01/05/25

Description

79L05 5V fixed 3-terminal negative voltage regulator delivers up to 100mA output current & is equipped with internal limiting + thermal shutdown features for overload immunity. Implementing this device at point-of-source removes the complexity of single point regulation methods + reduces noise. In replacement of a Zener diode/resistor combination, the device improves output impedance by x2 order of magnitude and delivers lower bias current with lower noise. The 79L05 can also be used with power-pass elements to make high-current voltage regulators.

Ordering Information

The following part suffixes apply:

- No suffix MIL-STD-883 /2010B Visual Inspection
- "H" MIL-STD-883 /2010B Visual Inspection
 + MIL-PRF-38534 Class H LAT
- "K" MIL-STD-883 /2010A Visual Inspection (Space)
 + MIL-PRF-38534 Class K LAT

LAT = Lot Acceptance Test.

For further information on LAT process flows see below.

www.siliconsupplies.com\quality\bare-die-lot-qualification

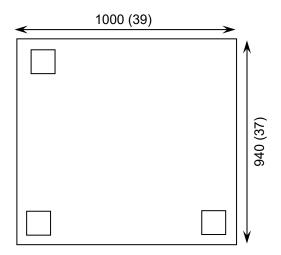
Supply Formats:

- Default Die in Waffle Pack (400 per tray capacity)
- Sawn Wafer on Tape On request
- Unsawn Wafer On request
- With Ti/Ni/Ag Back Metal On request
- In Metal or Ceramic package On request

Features:

- ±5% V_{OUT} tolerance
- 100mA Output Current
- Internal thermal overload protection
- Internal short circuit current limit
- Full Military Temperature Range
- Positive Voltage complement is 78L05

Die Dimensions in µm (mils)



Mechanical Specification

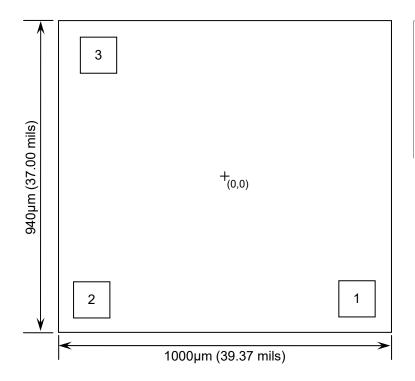
Die Size (Unsawn)	1000 x 940 39 x 37	μm mils	
Minimum Bond Pad Size	110 x 110 4.33 x 4.33	μm mils	
Die Thickness	280 (±20) 11 (±0.8)	μm mils	
Top Metal Composition	Al-Si-Cu 3μm		
Back Metal Composition	N/A – Bare Si		





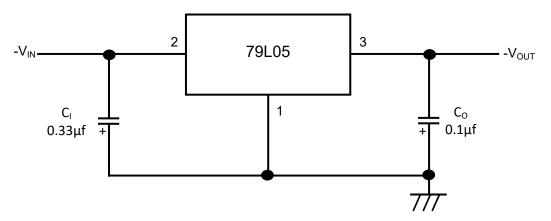
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Pad Layout and Functions



DAD	PAD FUNCTION	COORDINATES (µm)			
PAD		X	Y		
1	GND	395	-363		
2	-V _{IN}	-398	-369		
3	-V _{OUT}	-383	369		
CONNECT CHIP BACK TO -VIN					

Typical Application



 C_l is required if the regulator is located an appreciable distance from power supply filter. C_0 is not required for stability; however it does improve transient response. For optimum stability and transient response locate C_l C_0 as close as possible to the regulator.





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Absolute Maximum Ratings

PARAMETER	SYMBOL	VALUE	UNIT	
Input Voltage	V _{IN}	-30	V	
Power Dissipation ¹	P _D	625	mW	
Operating Temperature Range	-	-55 to 125	°C	
Maximum Junction Temperature	T _J	150	°C	
Storage Temperature	T _{STG}	-65 to 150	°C	

Recommended Operating Conditions

PARAMETER	SYMBOL	MIN	MAX	UNIT
Input Voltage	V _{IN}	-7	-20	V
Output Current	I _{OUT}	-	100	mA
Operating Temperature Range	T _J	-55	125	°C

DC Electrical Characteristics V_I = -10V, I_{OUT}=40mA,C_I=0.33µF, C_O=0.1µf, 0°C<T_J<+125°C(unless noted otherwise)

PARAMETER	SYMBOL	TEST CONDITIONS	MIN	TYP	MAX	UNITS	
Output Voltage	V _{OUT}	$T_J = 25^{\circ}\text{C}, I_O = 40\text{mA}$	-4.60	-5.00	-5.40	V	
		$1\text{mA} \le I_{\text{OUT}} \le 40\text{mA}, -7\text{V} \ge V_{\text{IN}} \ge -20\text{V}$	-4.50	-5.00	-5.50		
		$1\text{mA} \le I_{\text{OUT}} \le 70\text{mA}, V_{\text{IN}} = -10\text{V}$	-4.50	-5.00	-5.50		
Line Regulation ΔV _{OUT}	۸۱/	$-7V \ge V_{IN} \ge -20V, T_J = 25^{\circ}C, I_O = 40mA$	-	-	200		
	ΔVOUT	$-8V \ge V_{IN} \ge -20V, T_J = 25^{\circ}C, I_O = 40mA$	-	-	150	mV	
Load Regulation	ΔV _{OUT}	$1\text{mA} \le I_{\text{OUT}} \le 100\text{mA}, T_{\text{J}} = 25^{\circ}\text{C}$	-	-	60		
		$1\text{mA} \le I_{\text{OUT}} \le 40\text{mA}, T_{\text{J}} = 25^{\circ}\text{C}$	-	-	30		
Input Bias Current	I _B	$T_J = 25^{\circ}C$	-	3.5	6.0	mA	
		T _J = 125°C	-	-	5.5		
Input Bias Current		-8V ≥ V _{IN} ≥ -20V	-	-	1.5	mΛ	
Change	ΔI_{B}	1mA ≤ I _{OUT} ≤ 40mA	-	-	0.2	mA	
Output Noise Voltage	e _N	10Hz ≤ f ≤ 100KHz, T _J = 25°C	-	40	-	μV_{RMS}	
Ripple Rejection	RR	f = 120Hz,-8V ≥ V _{IN} ≥ 18V,T _J = 25°C	40	49	-	dB	
Dropout Voltage	V _D	$V_{IN} - V_{OUT}$	-	1.7	-	V	

^{1.} Value measured in TO-92 package applicable only for DC power dissipation permitted by absolute maximum ratings. Results in die form are dependent on die attach and assembly method.





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